



SMD1812 Series

Surface Mount PTC



Application:	All high-density boards
Product Features:	Small surface mount, Solid state Faster time to trip than standard SMD devices Lower resistance than standard SMD devices
Operation Current:	100mA~3.0A
Maximum Voltage:	6V~60VDC
Temperature Range:	-40°C to 85°C
Agency Recognition:	UL, C-UL, TÜV

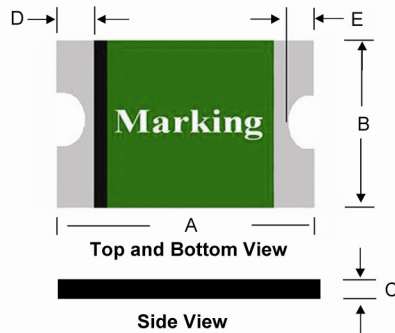
Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Maximum Current	Typical Power	Max Time to Trip		Resistance Tolerance	
						Current	Time	RMIN	R1MAX
						Amp	Sec	ohms	ohms
SMD1812-010-60R	0.10	0.30	60	100	0.8	8.0	0.020	1.600	15.00
SMD1812-014-60R	0.14	0.30	60	100	0.8	8.0	0.008	1.200	6.500
SMD1812-020-30R	0.20	0.40	30	100	0.8	8.0	0.020	0.800	5.000
SMD1812-020-60R	0.20	0.40	60	100	0.8	8.0	0.020	0.800	5.000
SMD1812-030-30R	0.30	0.60	30	100	0.8	8.0	0.100	0.200	1.750
SMD1812-035-16R	0.35	0.70	16	100	0.8	8.0	0.100	0.320	1.500
SMD1812-035-30R	0.35	0.70	30	100	0.8	8.0	0.100	0.320	1.500
SMD1812-050-16R	0.50	1.00	16	100	0.8	8.0	0.150	0.150	1.000
SMD1812-050-30R	0.50	1.00	30	100	0.8	8.0	0.150	0.150	1.000
SMD1812-075-16R	0.75	1.50	16	100	0.8	8.0	0.200	0.110	0.450
SMD1812-075-24R	0.75	1.50	24	100	1.0	8.0	0.200	0.110	0.290
SMD1812-075-33R	0.75	1.50	33	100	1.0	8.0	0.200	0.110	0.400
SMD1812-110-8R	1.10	2.20	8	100	0.8	8.0	0.300	0.040	0.210
SMD1812-110-16R	1.10	2.20	16	100	0.8	8.0	0.500	0.060	0.180
SMD1812-110-24R	1.10	2.20	24	100	1.0	8.0	0.500	0.060	0.200
SMD1812-125-6R	1.25	2.50	6	100	0.8	8.0	0.400	0.050	0.140
SMD1812-125-16R	1.25	2.50	16	100	0.8	8.0	0.400	0.050	0.140
SMD1812-150-8R	1.50	3.00	8	100	0.8	8.0	0.500	0.040	0.110
SMD1812-150-12R	1.50	3.00	12	100	1.0	8.0	0.500	0.040	0.110
SMD1812-150-24R	1.50	3.00	24	100	1.0	8.0	1.500	0.040	0.120
SMD1812-160-8R	1.60	3.20	8	100	0.8	8.0	0.500	0.030	0.100
SMD1812-160-12R	1.60	3.20	12	100	1.0	8.0	1.000	0.030	0.100
SMD1812-160-16R	1.60	3.20	16	100	1.0	8.0	1.000	0.030	0.100
SMD1812-200-8R	2.00	3.50	8	100	1.0	8.0	2.000	0.020	0.070
SMD1812-200-16R	2.00	3.50	16	100	1.0	8.0	5.000	0.020	0.085
SMD1812-260-8R	2.60	5.00	8	100	1.0	8.0	2.500	0.015	0.047
SMD1812-260-13R	2.60	5.00	13.2	100	1.3	8.0	5.000	0.015	0.050
SMD1812-260-16R	2.60	5.00	16	100	1.3	8.0	5.000	0.015	0.050
SMD1812-300-6R	3.00	5.00	6	100	1.0	8.0	4.000	0.012	0.040

IH=Hold current-maximum current at which the device will not trip at 23°C still air.
 IT=Trip current-minimum current at which the device will always trip at 23°C still air.
 V MAX=Maximum voltage device can withstand without damage at its rated current.
 I MAX= Maximum fault current device can withstand without damage at rated voltage (V max).
 Pd=Typical power dissipated from device when in the tripped state in 23°C still air environment.
 RMIN=Minimum device resistance at 23°C.
 R1MAX=Maximum device resistance at 23°C, 1 hour after tripping .
 Termination pad characteristics
 Termination pad materials: Tin-plated copper

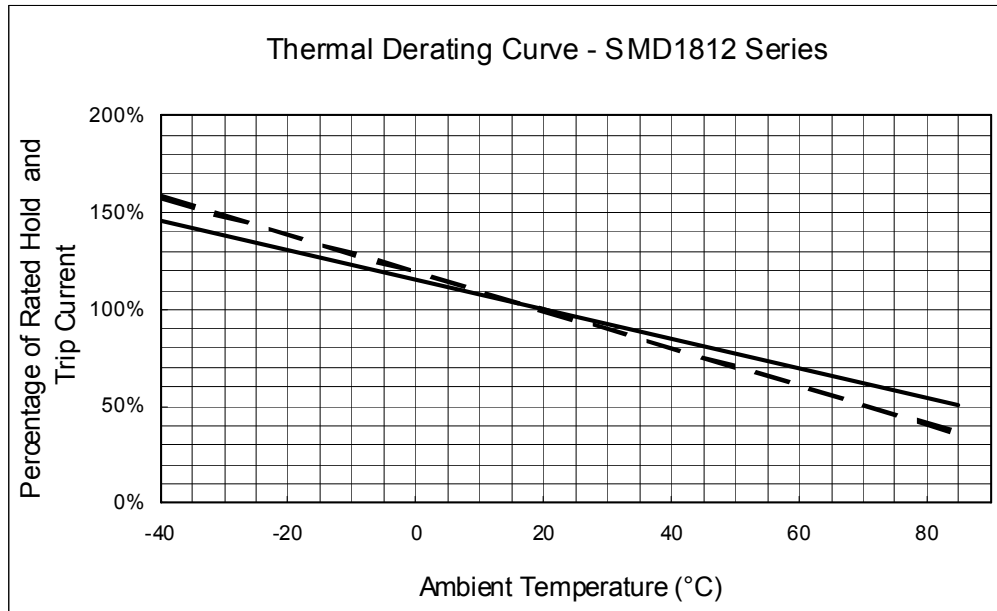
Specifications are subject to change without notice.

SMD1812 Product Dimensions (Millimeters)



Part Number	A		B		C		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
SMD1812-010-60R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
SMD1812-014-60R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
SMD1812-020-30R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
SMD1812-020-60R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
SMD1812-030-30R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
SMD1812-035-16R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
SMD1812-035-30R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
SMD1812-050-16R	4.37	4.73	3.07	3.41	0.35	0.65	0.30	0.95	0.25	0.65
SMD1812-050-30R	4.37	4.73	3.07	3.41	0.45	0.75	0.30	0.95	0.25	0.65
SMD1812-075-16R	4.37	4.73	3.07	3.41	0.35	0.65	0.30	0.95	0.25	0.65
SMD1812-075-24R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
SMD1812-075-33R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
SMD1812-110-8R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
SMD1812-110-16R	4.37	4.73	3.07	3.41	0.25	0.90	0.30	0.95	0.25	0.65
SMD1812-110-24R	4.37	4.73	3.07	3.41	0.80	1.30	0.25	0.95	0.25	0.65
SMD1812-125-6R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
SMD1812-125-16R	4.37	4.73	3.07	3.41	0.50	1.00	0.30	0.95	0.25	0.65
SMD1812-150-8R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
SMD1812-150-12R	4.37	4.73	3.07	3.41	0.60	1.10	0.25	0.95	0.25	0.65
SMD1812-150-24R	4.37	4.73	3.07	3.41	0.60	1.55	0.25	0.95	0.25	0.65
SMD1812-160-8R	4.37	4.73	3.07	3.41	0.25	0.90	0.30	0.95	0.25	0.65
SMD1812-160-12R	4.37	4.73	3.07	3.41	0.60	1.35	0.25	0.95	0.25	0.65
SMD1812-160-16R	4.37	4.73	3.07	3.41	0.60	1.35	0.25	0.95	0.25	0.65
SMD1812-200-8R	4.37	4.73	3.07	3.41	0.55	1.20	0.25	0.95	0.25	0.65
SMD1812-200-16R	4.37	4.73	3.07	3.41	0.60	1.55	0.25	0.95	0.25	0.65
SMD1812-260-8R	4.37	4.73	3.07	3.41	0.55	1.20	0.25	0.95	0.25	0.65
SMD1812-260-13R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
SMD1812-260-16R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
SMD1812-300-6R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65

Thermal Derating Curve

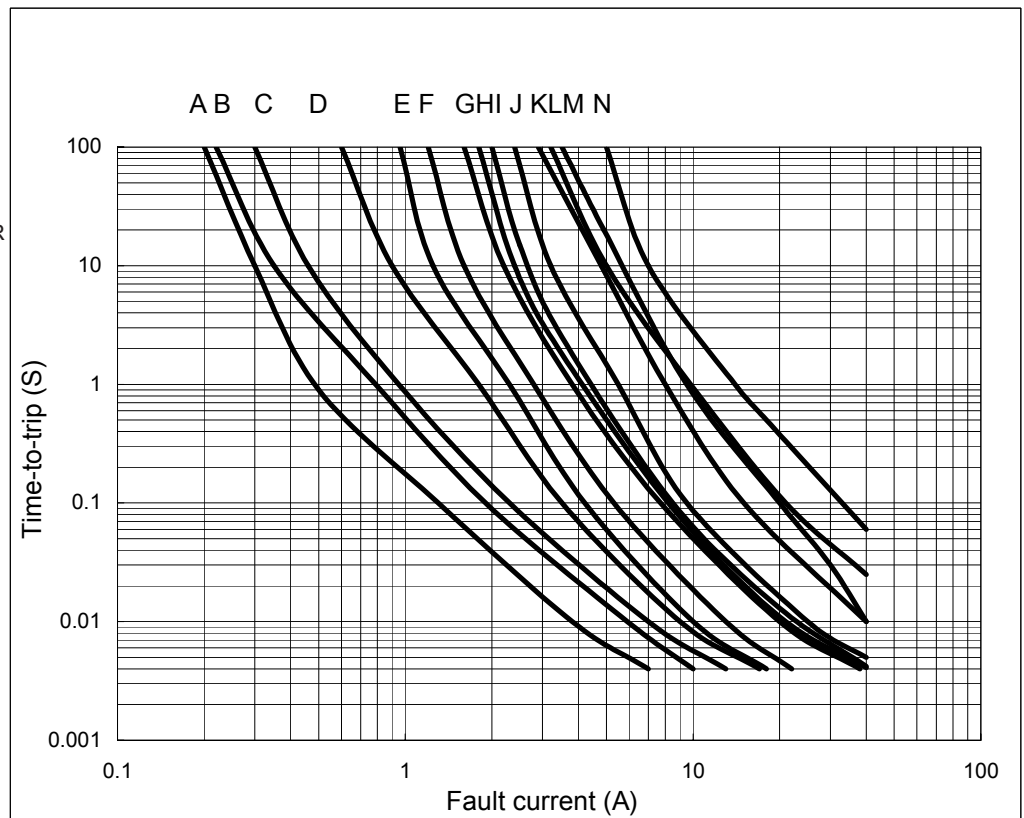


SMD1812-075-16R, 075-24R, 075-33R, 110-8R, 110-16R, 110-24R, 125-6R, 125-16R, 150-8R, 150-12R, 150-24R, 160-8R, 160-12R, 160-16R, 200-8R, 200-16R, 260-8R, 260-13R, 260-16R, 300-6R

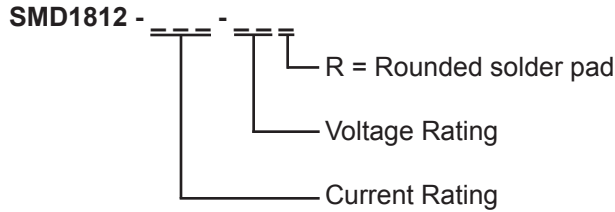
SMD1812-010-60R, 014-60R, 020-30R, 020-60R, 030-30R, 035-30R, 050-16R, 050-30R

Typical Time-To-Trip at 23°C

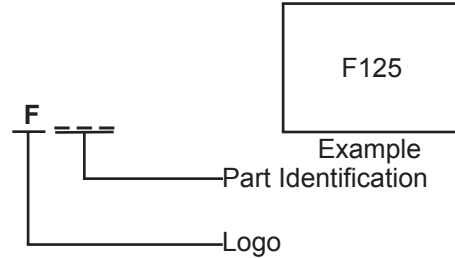
- A = SMD1812-010-60R
- B = SMD1812-014-60R
- C = SMD1812-020-30R / 020-60R
- D = SMD1812-030-30R
- E = SMD1812-035-16R / 035-30R
- F = SMD1812-050-16R / 050-30R
- G = SMD1812-075-16R / 075-24R / 075-33R
- H = SMD1812-110-8R / 110-16R / 110-24R
- I = SMD1812-125-6R / 125-16R
- J = SMD1812-150-8R / 150-12R / 150-24R
- K = SMD1812-160-8R / 160-12R / 160-16R
- L = SMD1812-200-8R / 200-16R
- M = SMD1812-260-8R / 260-13R / 260-16R
- N = SMD1812-300-6R



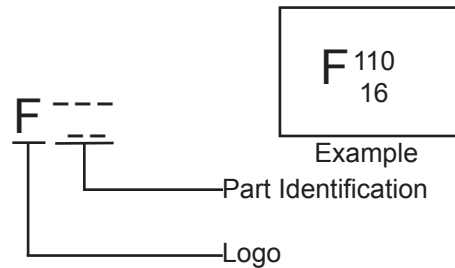
Part Numbering System



Part Marking System



Special Marking for SMD1812-010-60R, 014-60R, 020-30R, 030-30R, 035-16R, 050-16R, 075-16R, 110-8R, 125-6R, 150-8R, 160-8R, 200-8R, 260-8R, 300-6R



Standard Package

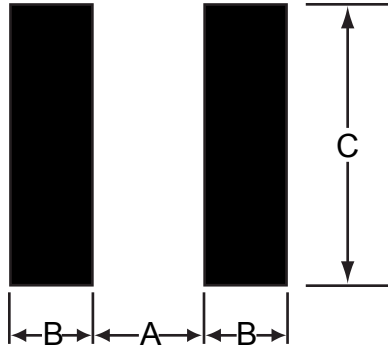
P/N	Reel / Tape
SMD1812-010-60R	2K
SMD1812-014-60R	2K
SMD1812-020-30R	2K
SMD1812-020-60R	2K
SMD1812-030-30R	2K
SMD1812-035-16R	2K
SMD1812-035-30R	2K
SMD1812-050-16R	2K
SMD1812-050-30R	2K
SMD1812-075-16R	2K
SMD1812-075-24R	1.5K
SMD1812-075-33R	1.5K
SMD1812-110-8R	2K
SMD1812-110-16R	2K
SMD1812-110-24R	1.5K

P/N	Reel / Tape
SMD1812-125-6R	2k
SMD1812-125-16R	1.5K
SMD1812-150-8R	2K
SMD1812-150-12R	2K
SMD1812-150-24R	2K
SMD1812-160-8R	2K
SMD1812-160-12R	2K
SMD1812-160-16R	2K
SMD1812-200-8R	2K
SMD1812-200-16R	2K
SMD1812-260-8R	2K
SMD1812-260-13R	1.5K
SMD1812-260-16R	1.5K
SMD1812-300-6R	1.5K

- 1- Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
- 2 -PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.
- 3- Avoid contact of PPTC device with chemical solvent. Prolonged contact will damage the device performance.

Pad Layouts, Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout.



Pad dimensions (millimeters)			
Device	A	B	C
	Nominal	Nominal	Nominal
SMD1812 Series	3.45	1.78	3.50

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C / second max.
Preheat: Temperature Min (T _{smin}) Temperature Max (T _{smax}) Time (t _{smin} to t _{smax})	150°C 200°C 60-180 seconds
Time maintained above: Temperature (T _L) Time (t _L)	217°C 60-150 seconds
Peak / Classification Temperature (T_p):	260°C
Time within 5°C of actual peak: Temperature (t _p)	20-40 seconds
Ramp-Down Rate:	6°C / second max.
Time 25°C to Peak Temperature:	8 minutes max.

SOLDER REFLOW

Due to "Lead Free" nature, Temperature and Dwelling Time for the soldering zone is higher than those for Regular. This may cause damage to other components

1. Recommended maximum paste thickness > 0.25mm.
2. Devices can be cleaned using standard methods and aqueous solvents.
3. Rework use standard industry practices.
4. Storage Environment: <30°C / 60%RH

CAUTION:

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.

